

HDMI Connectors

Electronics | Connectors

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Benefits

 \circ PA4T good flow (> PPA, = LCP) PA4T low moisture absorption



Details

ForTii® PA4T allows for reliable solutions due to its high melting temperature (ideal for reflow process), high mechanical performance (also after reflow soldering), a high dimensional stability (result from low, isotropic CLTE), a high co-planarity and low warpage after soldering, and good dielectrics due to low moisture uptake; ForTii® PA4T allow for cost effective solutions to due good processability and high flowability enabling thin walled designs; ForTii® PA4T allow for even more sustainable solutions with reduced environmental impact due to its lower carbon footprint as compared to alternative materials

Products

ForTii® F11

Seller represents and warrants exclusively that on the date of delivery by Seller the product shall be in conformity with the specifications agreed upon. Seller makes no other representations or warranties, whether express or implied.

Seller is not responsible or liable for the design of the products of the Customer and it is the responsibility of the Customer to determine that the Seller's product is safe, complies with

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Typical values are indicative only and are not to be construed as being binding specifications. Colorants in the product or other additives may cause significant variations in typical values.